

NCE6050IA

NCE N-Channel Enhancement Mode Power MOSFET

Description

The NCE6050IA uses advanced trench technology and design to provide excellent R_{DS(ON)} with low gate charge. It can be used in a wide variety of applications.

General Features

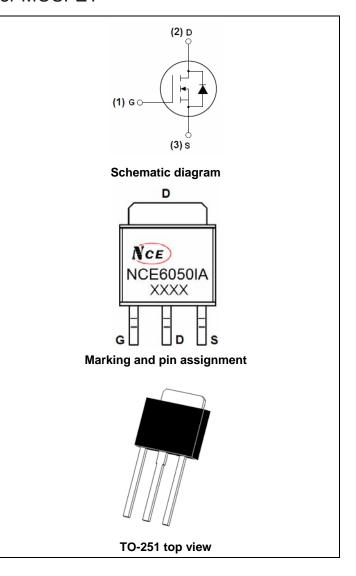
- V_{DS} =60V,I_D =50A $R_{DS(ON)}$ <20m Ω @ V_{GS} =10V
- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high E_{AS}
- Excellent package for good heat dissipation
- Special process technology for high ESD capability

Application

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply

100% UIS TESTED!

100% AVds TESTED!



Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCE6050IA	NCE6050IA	TO-251	-	-	-

Absolute Maximum Ratings (T_c=25 ℃ unless otherwise noted)

Parameter	Symbol	Limit	Unit
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Drain-Source Voltage	V _{DS}	60	V
Gate-Source Voltage	V _G S	±20	V
Drain Current-Continuous	I _D	50	Α
Drain Current-Continuous(T _C =100 ℃)	I _D (100℃)	35.4	А
Pulsed Drain Current	I _{DM}	200	А
Maximum Power Dissipation	P _D	85	W
Derating factor		0.56	W/℃
Single pulse avalanche energy (Note 5)	E _{AS}	300	mJ
Operating Junction and Storage Temperature Range	T_{J}, T_{STG}	-55 To 175	$^{\circ}$



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Thermal Characteristic

Electrical Characteristics (T_C=25 ℃ unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics			•			•
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	60	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =60V,V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	V _{GS(th)}	$V_{DS}=V_{GS}$, $I_{D}=250\mu A$	1.4	1.8	2.5	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =20A	-	13	20	mΩ
Forward Transconductance	g FS	V _{DS} =5V,I _D =20A	18	-	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	C _{lss}	\/ 20\/\/ 0\/	-	2050	-	PF
Output Capacitance	Coss	V_{DS} =30V, V_{GS} =0V,	-	158	-	PF
Reverse Transfer Capacitance	C _{rss}	F=1.0MHz	-	120	-	PF
Switching Characteristics (Note 4)	•		•			•
Turn-on Delay Time	t _{d(on)}		-	7.4	-	nS
Turn-on Rise Time	t _r	V_{DD} =30V, R_L =6.7 Ω	-	5.1	-	nS
Turn-Off Delay Time	t _{d(off)}	V_{GS} =10 V , R_{G} =3 Ω	-	28.2	-	nS
Turn-Off Fall Time	t _f		-	5.5	-	nS
Total Gate Charge	Q_g	\/ -20\/ L -20A	-	50		nC
Gate-Source Charge	Q_{gs}	$V_{DS}=30V,I_{D}=20A,$ $V_{GS}=10V$	-	6		nC
Gate-Drain Charge	Q_{gd}	V _{GS} =10V	-	15		nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =20A	-		1.2	V
Diode Forward Current (Note 2)	Is		-	-	50	Α
Reverse Recovery Time	t _{rr}	TJ = 25°C, IF =20A	-	28	-	nS
Reverse Recovery Charge	Qrr	$di/dt = 100A/\mu s^{(Note3)}$	-	40	-	nC
Forward Turn-On Time	t _{on}	Intrinsic turn-on time is negli	gible (turr	n-on is do	ominated b	y LS+LD)

Notes:

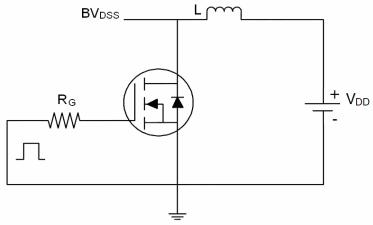
- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- **3.** Pulse Test: Pulse Width ≤ 300μ s, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production
- 5. EAS condition : Tj=25 $^{\circ}\text{C}$,VDD=30V,VG=10V,L=0.5mH,Rg=25 Ω



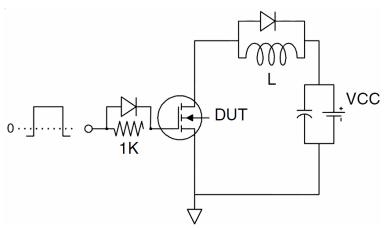
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Test Circuit

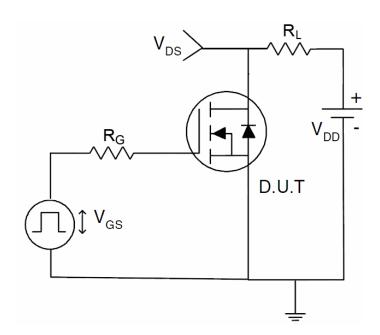
1) E_{AS} test Circuit



2) Gate charge test Circuit



3) Switch Time Test Circuit





Typical Electrical and Thermal Characteristics (Curves)

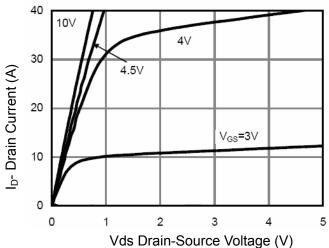


Figure 1 Output Characteristics

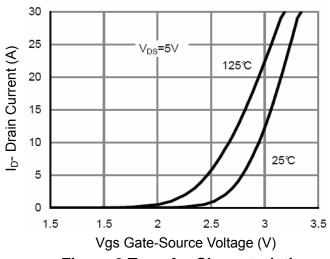


Figure 2 Transfer Characteristics

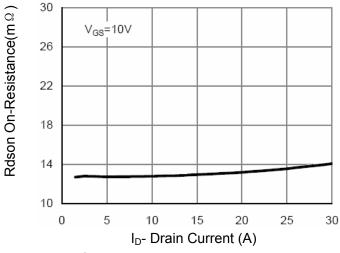


Figure 3 Rdson- Drain Current

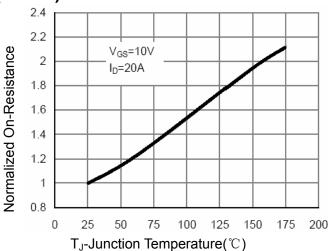


Figure 4 Rdson-Junction Temperature

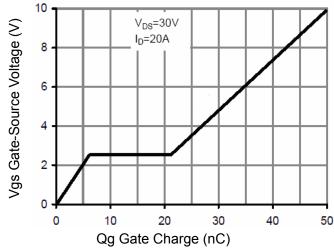


Figure 5 Gate Charge

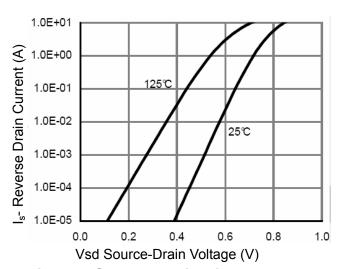
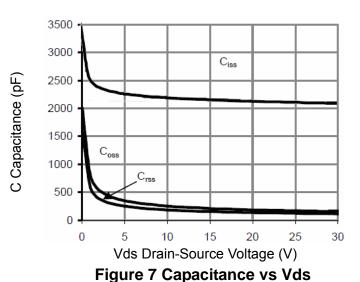


Figure 6 Source- Drain Diode Forward





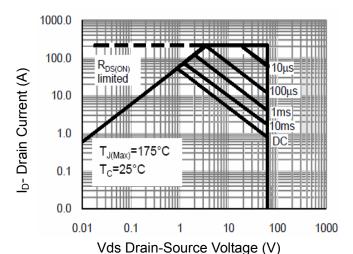


Figure 8 Safe Operation Area

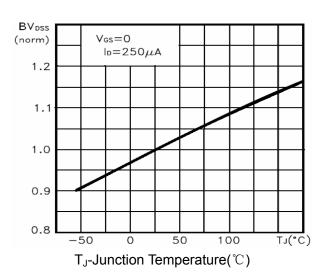


Figure 9 BV_{DSS} vs Junction Temperature

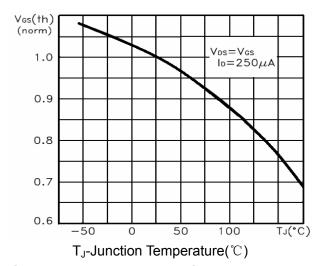


Figure 10 V_{GS(th)} vs Junction Temperature

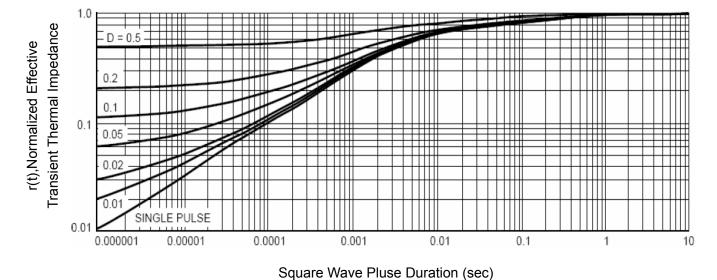
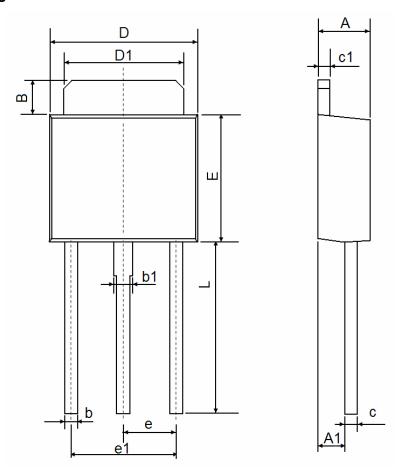


Figure 11 Normalized Maximum Transient Thermal Impedance



TO-251 Package Information



Symbol	Dimensions	In Millimeters	Dimensions In Inches		
	Min.	Max.	Min.	Max.	
А	2.200	2.400	0.087	0.094	
A1	1.050	1.350	0.042	0.054	
В	1.350	1.650	0.053	0.065	
b	0.500	0.700	0.020	0.028	
b1	0.700	0.900	0.028	0.035	
С	0.430	0.580	0.017	0.023	
c1	0.430	0.580	0.017	0.023	
D	6.350	6.650	0.250	0.262	
D1	5.200	5.400	0.205	0.213	
E	5.400	5.700	0.213	0.224	
е	2.300 TYP		0.091 TYP		
e1	4.500	4.700	0.177	0.185	
L	7.500	7.900	0.295	0.311	



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